

In the Claims:

1. (currently amended) A method of resin-encapsulating an  
2 electronic component mounted on a main surface of a board,  
3 using a mold pair having an upper mold and a lower mold,  
4 comprising the steps of:

5 attaching said board on said upper mold;

6 generating melted resin in a cavity provided in said  
7 lower mold; mold by melting a solid resin material in said  
cavity;

9 immersing said electronic component in said melted  
10 resin in said cavity by closing said mold pair; and

11 forming a resin [[mold]] molded product including said  
12 electronic component in a set resin by setting said melted  
13 resin to produce said set resin in said cavity.

1. (currently amended) The method of resin encapsulation  
2 according to claim 1, wherein in further comprising, before  
3 said step of generating melted resin, said melted resin is  
4 generated by heating a another step of placing said solid  
5 resin material placed in said cavity.

1. 3. (original) The method of resin encapsulation according to  
2 claim 1, wherein

3 an electrode of said board and an electrode of said  
4 electronic component are connected by a conductive material  
5 forming a loop in a prescribed plane; and

6               in said step of immersing said electronic component in  
7        said melted resin, said prescribed plane moves  
8        substantially vertically to a main surface of said melted  
9        resin.

1       4. (original) A method of manufacturing a semiconductor  
2       device, using the method of resin encapsulation according  
3       to claim 1.

1       5. (original) A method of resin-encapsulating an electronic  
2       component mounted on a main surface of a board, using a  
3       mold pair having an upper mold and a lower mold and a solid  
4       resin material for resin encapsulation, comprising the  
5       steps of:

6               placing said board on said lower mold;

7               placing said resin material on a main surface of said  
8       board such that said resin material is not in contact with  
9       a conductive material connecting an electrode of said board  
10      with an electrode of said electronic component;

11         closing said mold pair;

12         generating melted resin on the main surface of said  
13      board and enclosing said electronic component in said  
14      melted resin by heating said resin material; and

15         forming a resin mold product by setting said melted  
16      resin.

1       6. (original) The method of resin encapsulation according to  
2       claim 5, wherein

3                 said resin material has such size and shape that  
4       correspond to size and shape of said cavity; and

5                 said melted resin is generated by heat transmitted  
6       from said upper mold to said resin material.

1       7. (original) The method of resin encapsulation according to  
2       claim 5, wherein

3                 said resin material is formed such that a space formed  
4       by said board and said resin material encloses said  
5       electronic component, when said resin material is placed on  
6       the main surface of said board; and

7                 said space is set to have such a size that said resin  
8       material is not in contact with the conductive material  
9       connecting the electrode of said board with the electrode  
10      of said electronic component.

1       8. (original) A method of manufacturing a semiconductor  
2       device, using the method of resin encapsulation according  
3       to claim 5.

1       9. (currently amended) A solid resin material consisting of a  
2       solid resin material adapted, sized and shaped to be placed  
3       in a mold cavity provided in a mold pair, and adapted to be  
4       used as a raw material [[or]] for being melted in said

5       cavity to produce thereof a melted resin in a method of  
6       resin-encapsulating an electronic component mounted on a  
7       main surface of a board in said cavity by encapsulating  
8       said electronic component in said melted resin and setting  
9       said melted resin in said cavity, wherein said solid resin  
10      material has generated in a cavity provided in a mold pair,  
11      having such a size and a shape that correspond to a size  
12      and a shape of said cavity.

1       10. (currently amended) The resin material according to  
2       claim 9, formed adapted, sized and shaped such that a space  
3       formed by said board and said resin material encloses said  
4       electronic component, when said resin material is placed on  
5       the main surface of said board; wherein said space is set  
6       to have such a size that said resin material is not in  
7       contact with [[the]] a conductive material connecting  
8       [[the]] an electrode of said board with [[the]] an  
9       electrode of said electronic component.

1       11. (original) The resin material according to claim 9, wherein  
2       a notch is formed in said resin material.

1       12. (new) The resin material according to claim 9, being a  
2       solid plate consisting of said solid resin material and  
3       having a stepped sectional shape with stepped side walls.

1       13. (new) The method of resin encapsulation according to claim  
2       1, wherein said step of placing said solid resin material  
3       in said cavity comprises transporting and depositing said  
4       solid resin material into said cavity using a  
5       vacuum-holding conveyor.

**[RESPONSE CONTINUES ON NEXT PAGE]**

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- 8 -